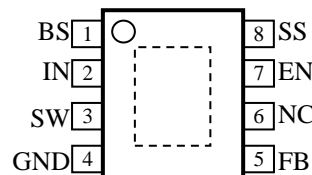
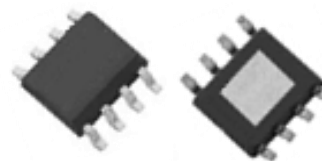


### General Descriptions

The NR885K series is synchronous buck regulator ICs integrates High-side and Low-side power MOSFETs. With the current mode control, ultra low ESR capacitors such as ceramic capacitors can be used. The ICs have protection functions such as Over-Current Protection (OCP), Under-Voltage Lockout (UVLO) and Thermal Shutdown (TSD). An adjustable Soft-Start by an external capacitor prevents the excessive inrush current at turn-on the regulator. The ICs integrate phase compensation circuit which reduces the number of external components and simplifies the design of customer application. The ON/OFF pin (EN Pin) turns the regulator on or off and helps to achieve low power consumption requirements. The NR885K series is available in an 8-pin HSOP8 package with an exposed thermal pad on the back side.

### Package

- HSOP8  
Thermally enhanced 8-Pin package



### Features & Benefits

- Current mode PWM control
- Up to 95% efficiency
- Stable with low ESR ceramic output capacitors
- Built-in protection function
  - Over Current Protection (OCP)
  - Thermal Shutdown (TSD)
  - Under Voltage Lockout (UVLO)
- Built-in phase compensation
- Adjustable Soft-Start with an external capacitor
- Turn ON/OFF the regulator function

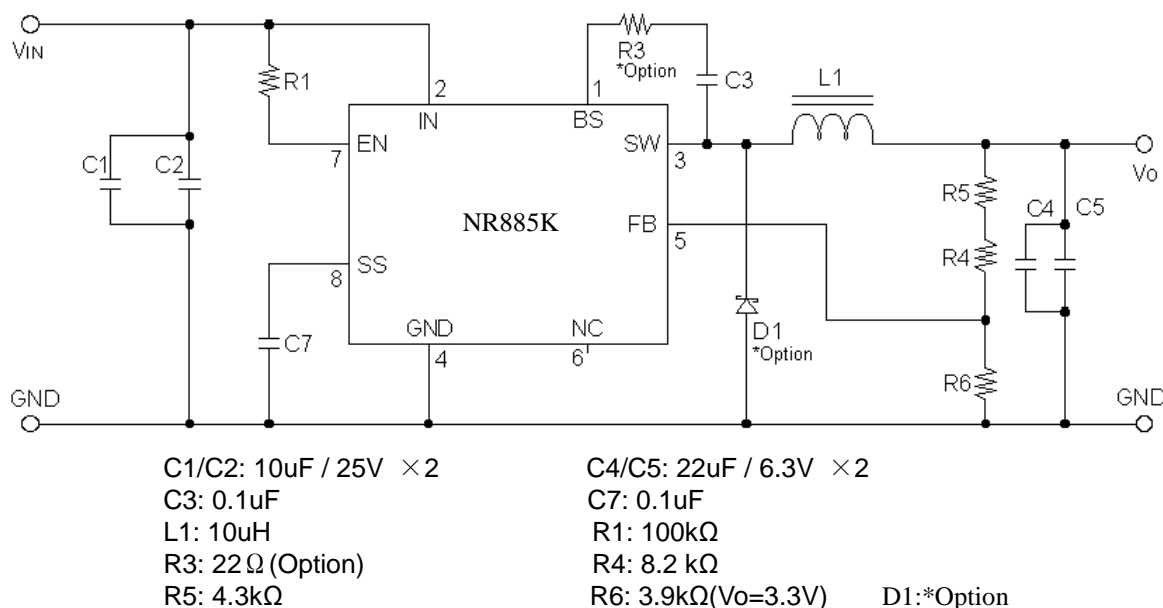
### Electrical Characteristics

- 3A output current
- Operating input range  $V_{IN} = 4.5V \sim 18V$
- Output adjustable  $V_O = 0.8V \sim 14V$
- Fixed 350kHz frequency

### Applications

- LCD TV / Blu-Ray / Set top box
- Green Electronic products
- Other power supply

### Typical Application Circuit



**Absolute Maximum Ratings**

Parameter	Symbol	Ratings	Units	Condition
DC input voltage	$V_{IN}$	20	V	
Power dissipation <sup>(1)</sup>	$P_D$	1.69	W	Glass-epoxy board mounting in a 30×30mm. (copper area in a 25×25mm) Max $T_J = 150^{\circ}\text{C}$
Junction temperature <sup>(2)</sup>	$T_J$	-40 to 150	$^{\circ}\text{C}$	
Storage temperature	$T_S$	-40 to 150	$^{\circ}\text{C}$	
Thermal resistance (junction- Pin No. 4)	$\theta_{JP}$	40	$^{\circ}\text{C} / \text{W}$	
Thermal resistance (junction-ambient air)	$\theta_{JA}$	74	$^{\circ}\text{C} / \text{W}$	Glass-epoxy board mounting in a 30×30mm. (copper area in a 25×25mm)

<sup>(1)</sup> Limited by thermal shutdown.

<sup>(2)</sup> The temperature detection of thermal shutdown is about 160°C

**Recommended Operating Conditions <sup>(3)</sup>**

Parameter	Symbol	Ratings		Units	Condition
		MIN	MAX		
DC input voltage <sup>(4)</sup>	$V_{IN}$	$V_O+3$	18	V	
DC output current <sup>(5)</sup> <sup>(6)</sup>	$I_O$	0	3.0	A	
Output voltage	$V_O$	0.8	14	V	
Ambient operating temperature <sup>(6)</sup>	$T_{op}$	-40	85	$^{\circ}\text{C}$	

<sup>(3)</sup> Recommended operating range indicates conditions which are required for maintaining normal circuit functions shown in Electrical Characteristics.

<sup>(4)</sup> The minimum value of input voltage is taken as the larger one of either 8v or " $V_{out}+3v$ ."

In the case of  $V_{IN}=V_O+1 \sim V_O+3V$ , it is set to  $I_{OUT}=2A$  MAX.

<sup>(5)</sup> Recommended circuit refers to Typical Application Circuit.

<sup>(6)</sup> To be used within the allowable package power dissipation characteristics.

## Electrical Characteristics

(7)

Ta = 25°C

Parameter		Symbol	Ratings			Units	Test conditions
			MIN	TYP	MAX		
Reference voltage		$V_{REF}$	0.784	0.800	0.816	V	$V_{IN} = 12V, I_O = 1.0A$
Output voltage temperature coefficient		$\Delta V_{REF} / \Delta T$	—	$\pm 0.05$	—	mV/°C	$V_{IN} = 12V, I_O = 1.0A$ -40°C to +85°C
Switching frequency		$f_{SW}$	280	350	420	kHz	$V_{IN} = 12V, V_O = 3.3V, I_O = 1A$
Line regulation		(8) $V_{Line}$	—	50	—	mV	$V_{IN} = 6.3V \sim 18V, V_O = 3.3V, I_O = 1A$
Load regulation		(8) $V_{Load}$	—	50	—	mV	$V_{IN} = 12V, V_O = 3.3V, I_O = 0.1A \sim 3.0A$
Over current protection starting current		$I_S$	3.1	—	6.0	A	$V_{IN} = 12V, V_O = 3.3V$
Supply Current		$I_{IN}$	—	6	—	mA	$V_{IN} = 12V$ $V_{EN} = 10k\Omega$ pull up to $V_{IN}$
Shutdown Supply Current		$I_{IN(off)}$	0	—	10	$\mu A$	$V_{IN} = 12V, I_O = 0A, V_{EN} = 0V$
SS Pin	Source current at low level voltage	(9) $I_{EN/SS}$	6	10	14	$\mu A$	$V_{SS} = 0V, V_{IN} = 12V$
	High level voltage	(9) $V_{SSH}$	—	3.0	—	V	$V_{IN} = 12V$
EN Pin	Sink current	$I_{EN}$	—	50	100	$\mu A$	$V_{EN} = 10V$
	Threshold voltage	$V_{C/EH}$	0.7	1.4	2.1	V	$V_{IN} = 12V$
Max on-duty		(10) $D_{MAX}$	—	90	—	%	
Minimum on-time		(11) $T_{ON(MIN)}$	—	150	—	nsec	
Thermal shutdown threshold temperature		(10) $TSD$	151	165	—	°C	
Thermal shutdown restart hysteresis of temperature		(10) $TSD_{hys}$	—	20	—	°C	

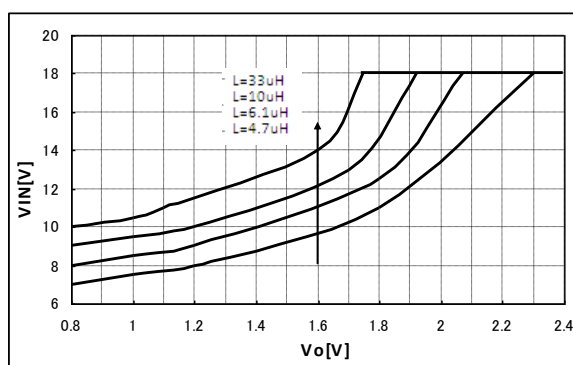
(7) Electrical characteristics indicate specific limits, which are guaranteed when IC is operated under the measurement conditions shown above in the circuit diagram (refer to 4-3 (p.7) ).

(8) Efficiency is calculated by the following equation.

(9) No.4 terminal is a EN/SS terminal to enable soft start by connecting a capacitor.

(10) This value is designed to guarantee value.

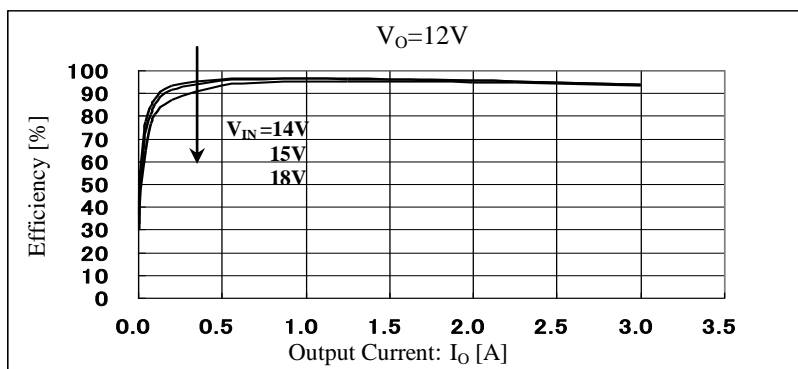
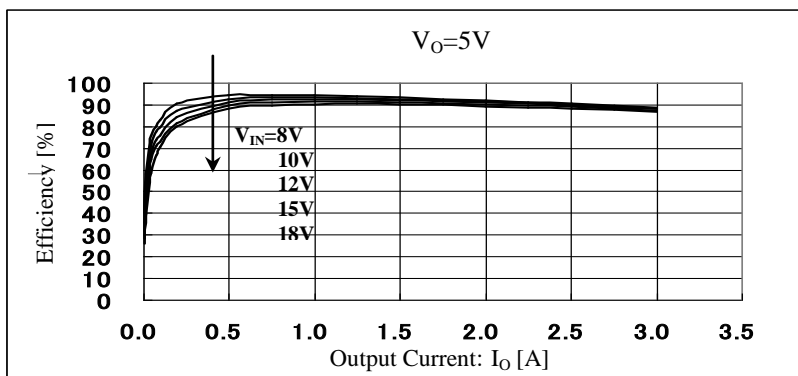
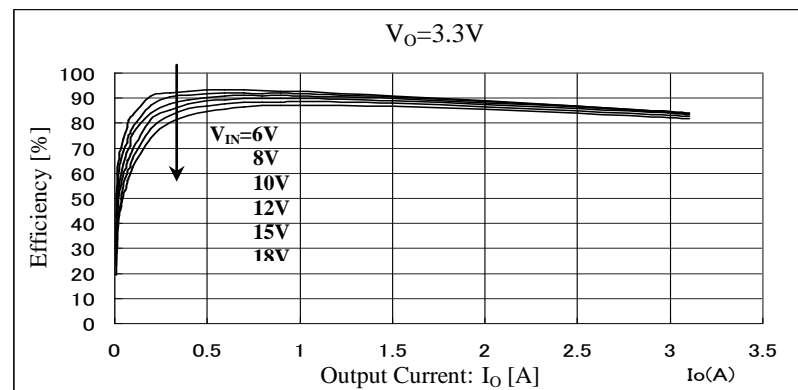
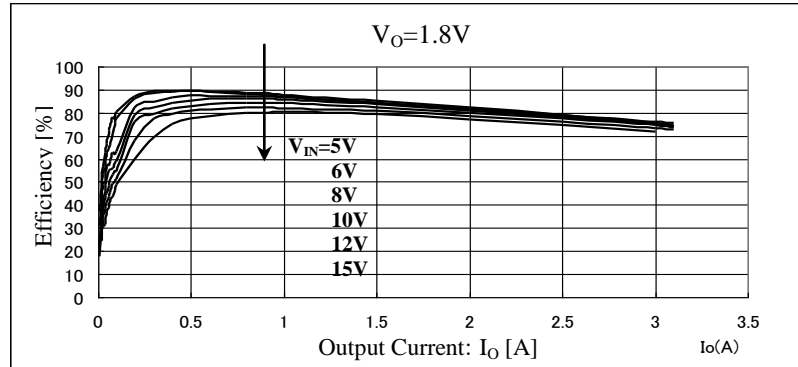
(11) The I/O characteristic graph of the figure below shows the I/O condition limited by the  $D_{MIN}$ . Be effective only if output current is less than 100mA.



## Typical Performance Characteristics

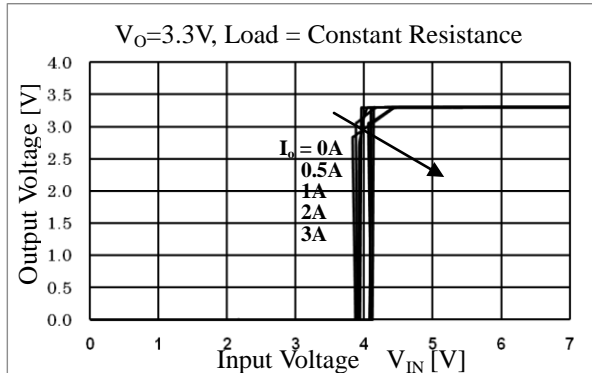
### NR885K Typical Performance Characteristics

#### Efficiency

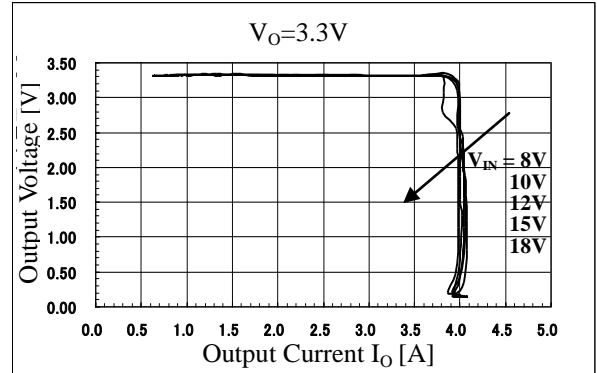


## NR885K Typical Performance Characteristics

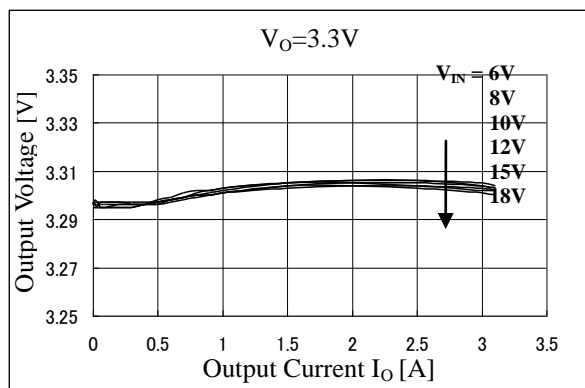
**Output startup**



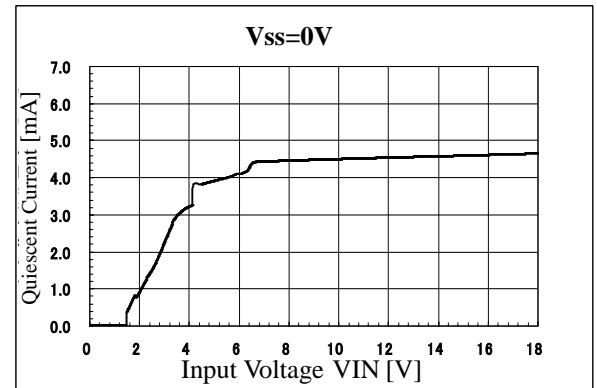
**Over Current Protection**



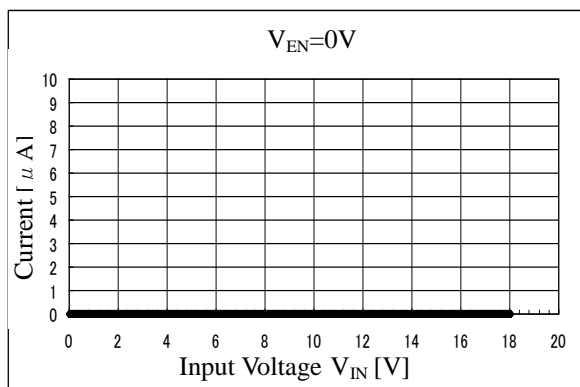
**Load Regulation:  $V_{Load}$**



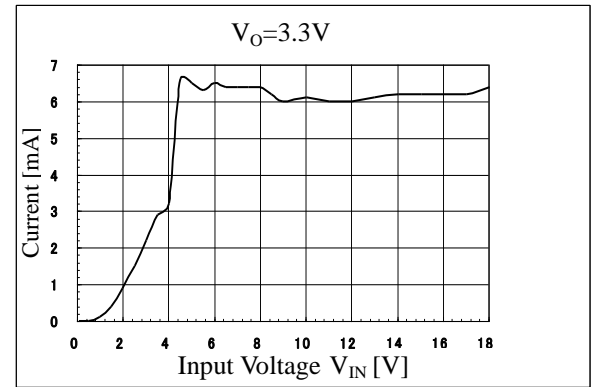
**Quiescent Current**

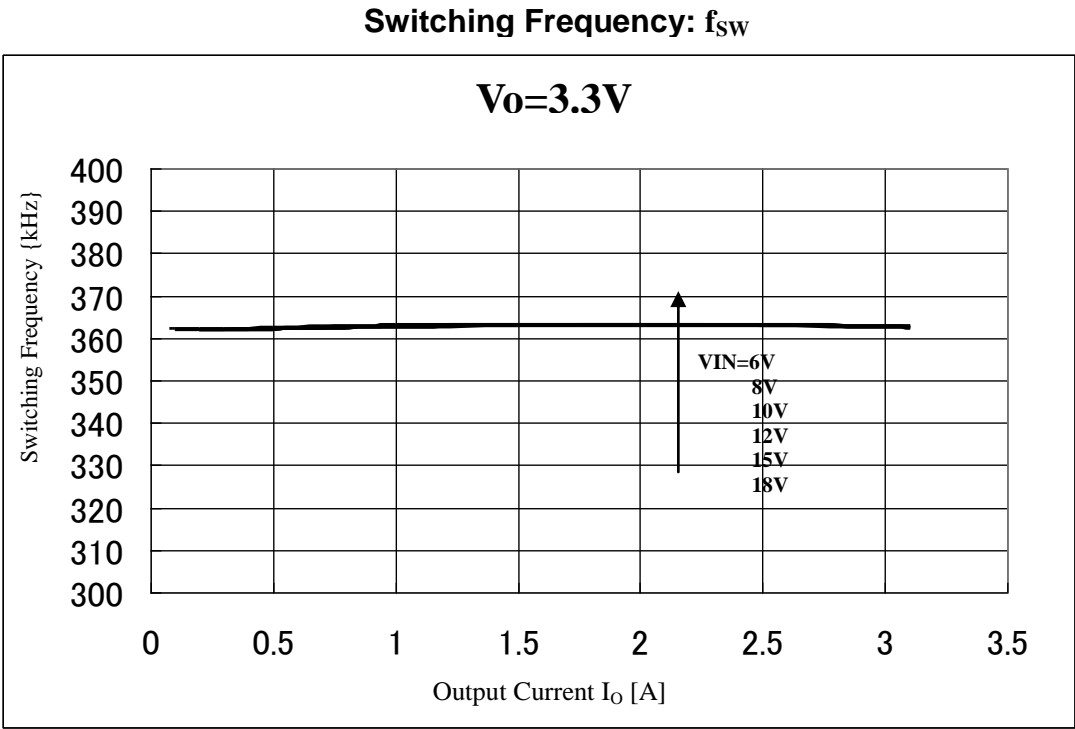


**Shutdown Supply Current :  $I_{IN(off)}$**

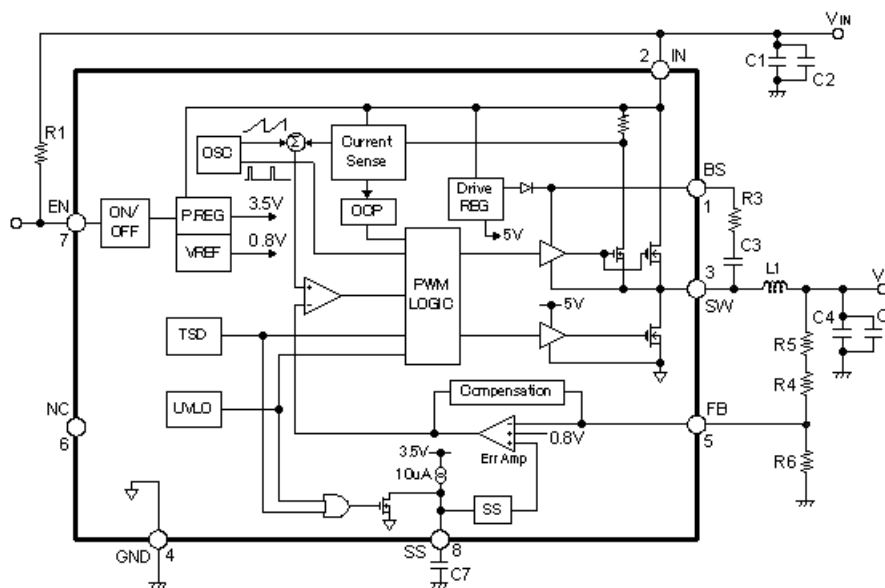


**Supply Current :  $I_{IN}$**

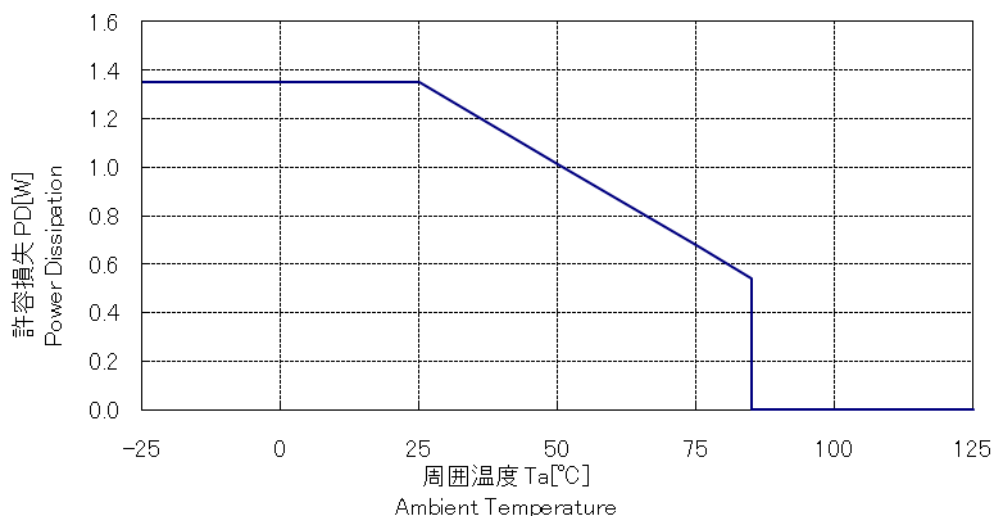




## Functional Block Diagram



## Allowable package power dissipation



## NOTES

- 1) Glass-epoxy board mounting in a 30×30mm
- 2) copper area : 25×25mm
- 3) The power dissipation is calculated at the junction temperature 125 °C
- 4) Losses can be calculated by the following equation.  
As the efficiency is subject to the input voltage and output current, it shall be obtained from the efficiency curve and substituted in percent
- 5) Thermal design for D1 shall be made separately.

V<sub>O</sub>: Output voltageV<sub>IN</sub>: Input voltageI<sub>O</sub>: Output current

η x : Efficiency (%)

$$P_D = V_O \times I_O \left( \frac{100}{\eta x} - 1 \right)$$

### External Components Design Guide

#### (1)Diode D1

- Flywheel diode D1 can be connected to enhance the efficiency.
- The schottky-barrier diode must be used for D1. If other diodes like fast recovery diodes are used, IC may be damaged because of the reverse voltage applied by the recovery voltage or ON voltage.

#### (2)Choke coil L1

- If the winding resistance of the choke coil is too high, the efficiency may go down to the extent that it is out of the rating.
- As the start current of the over current protection is approximately 4A, attention must be paid to the heating of the choke coil by the magnetic saturation due to overload or short-circulated load.

#### (3)Capacitor C1( C2), C4(C5), C7

- As large ripple currents across C1 (C2) and C4 (C5), capacitors with high frequency and low impedance for SMPS must be used. Especially when the impedance of C4 (C5) is high, the switching waveform may not be normal at low temperature.
- C7 is a capacitor for soft start. A soft-start controls the over-shoot of the output voltage rising and rush current.

#### (4)Resistor R4, R5, R6

- R4, R5, R6 are resistor to the Output Voltage.  $I_{ADJ}$  is required to set to 0.2mA.
- R4, R5, R6 are calculated by the equation (1).

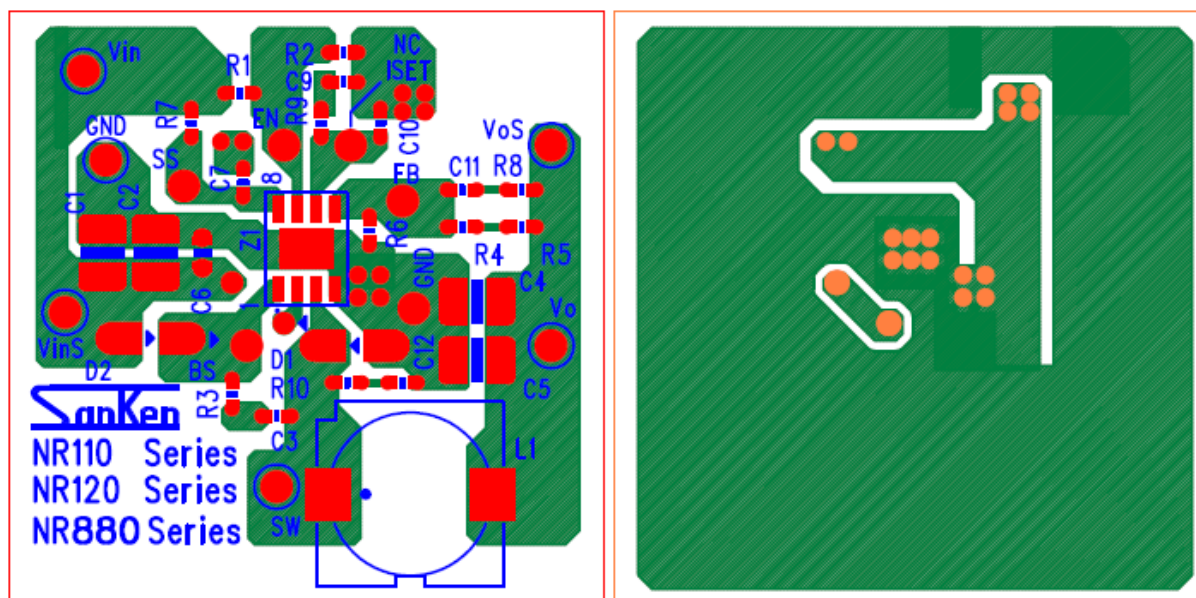
$$R4 + R5 = \frac{(V_O - V_{FB})}{I_{ADJ}} = \frac{(V_O - 0.8)}{0.2 \times 10^{-3}} (\Omega), \quad R6 = \frac{V_{FB}}{I_{ADJ}} = \frac{0.8}{0.2 \times 10^{-3}} \div 4.0k(\Omega) \quad \text{----- (1)}$$

In order to have optimum operating condition, each component must be connected with the minimum distance.



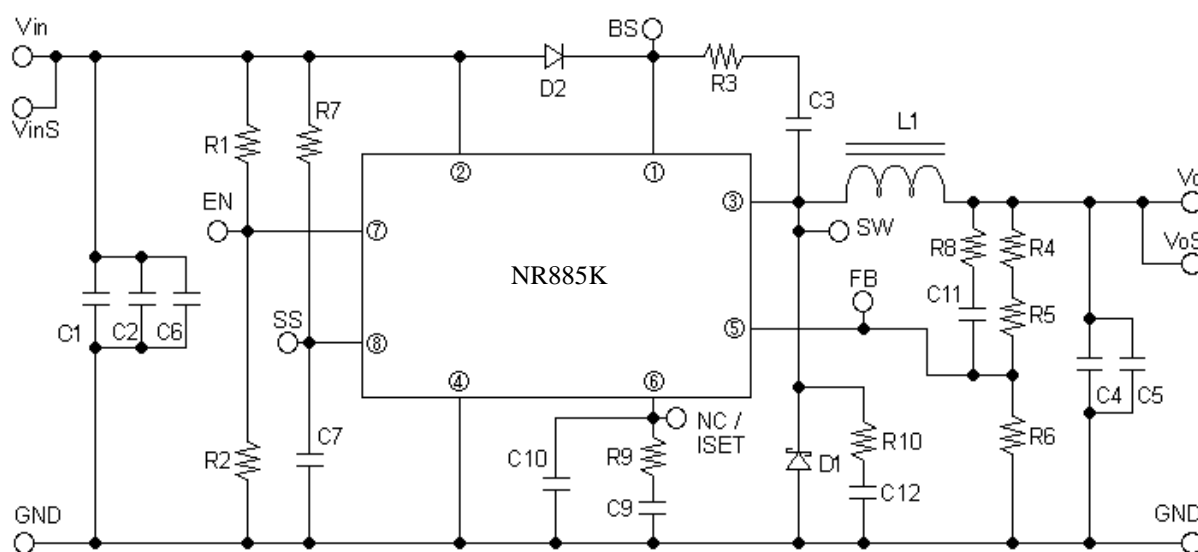
## PCB Layout & Recommended Land Pattern

- (1) Each ground of all components is connected as close as possible to the Pin No.4 at one point.
- (2) To help heat dissipation, connect a large copper plane to exposed pad on the back side of the package.  
The copper plane is required for GND



Front Side: Component Side (double sided board)

Back Side: GND Side (double sided board)

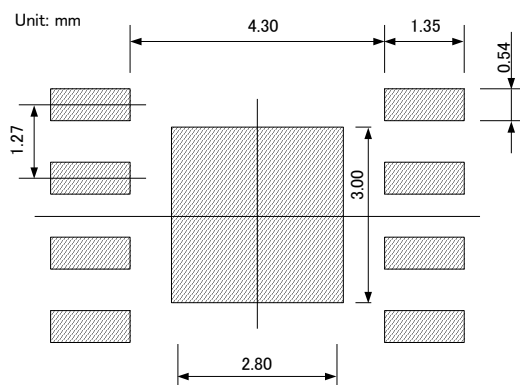


### Demo-board circuit-diagram

As for the part number of the demonstration board "circuit-diagram", a circuit board concerned doesn't partly fit each other with the above application circuit example and so on for NR110, NR120 and the NR880 series common use. Approve it in advance. C9, R9 and C10 aren't used in the NR880 series. And, D1, D2, R3, R8,R10, C11 and C12 are options.

NOTES:

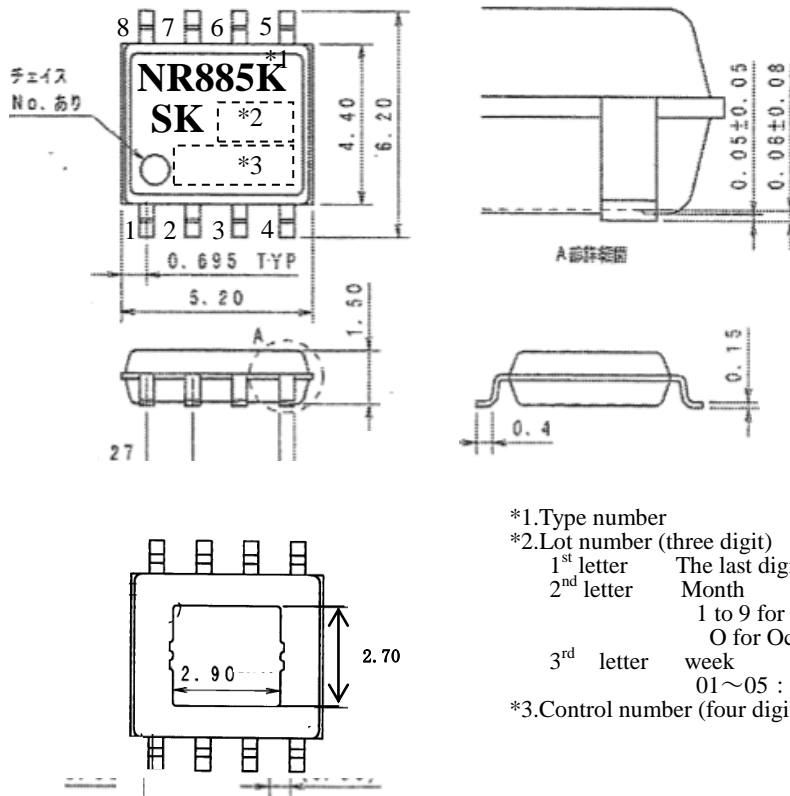
Real size of the PCB is 60mm×60mm



Recommended land pattern

## Package Outline

HSOP8 package



- \*1.Type number  
 \*2.Lot number (three digit)  
     1<sup>st</sup> letter   The last digit of year  
     2<sup>nd</sup> letter   Month  
                   1 to 9 for Jan. to Sept.,  
                   O for Oct. N for Nov. D for Dec.  
     3<sup>rd</sup> letter   week  
                   01~05 : Arabic Numerical  
 \*3.Control number (four digit)

### PIN Assignment

- 1.BS
- 2.IN
- 3.SW
- 4.GND
- 5.FB
- 6.NC
- 7.EN
- 8.SS

## Appearance

The body shall be clean and shall not bear any stain, rust or flaw.

## Marking

The type number and lot number shall be marked on the body by leaser which shall not be unreadable easily.

## OPERATING PRECAUTIONS

Reliability can be affected adversely by improper storage environments and handling methods. Please observe the following cautions.

### Heat dissipation and reliability

Thermal performance of the surface mount package IC depends on the material and area size of PCB and its copper plane. Design thermal condition with sufficient margin

### Parallel operation

The parallel operation to increase the current is not available.

### Thermal shut down

The NR111E has a thermal protection circuit.

This circuit protects the IC from the heat generation by the over load.

This circuit cannot guarantee the long-term reliability against the continuously over load status.

### Cautions for Storage

- Ensure that storage conditions comply with the standard temperature (5 to 35°C) and the standard relative humidity (around 40 to 75%); avoid storage locations that experience extreme changes in temperature or humidity.
- Avoid locations where dust or harmful gases are present and avoid direct sunlight.
- Reinspect for rust on leads and solderability of products that have been stored for a long time.

### Cautions for Testing and Handling

- When tests are carried out during inspection testing and other standard test periods, protect the products from power surges from the testing products, shorts between the product pins, and wrong connections. In addition, avoid tests exceeded ratings

### Soldering

When soldering the products, please be sure to minimize the working time, within the following limits.

- Reflow    Preheat ; 180°C / 90±30s  
              Heat ; 250°C / 10±1s (260°C peak ,2times)
- Soldering iron ; 380±10°C / 3.5±0.5s (1time)

### Electrostatic Discharge

- When handling the products, the operator must be grounded. Grounded wrist straps worn should have at least 1MΩ of resistance from the operator to ground to prevent shock hazard, and it should be placed near the operator.
- Workbenches where the products are handled should be grounded and be provided with conductive table and floor mats.
- When using measuring equipment such as a curve tracer, the equipment should be grounded.
- When soldering the products, the head of a soldering irons or the solder bath must be grounded in order to prevent leak voltages generated by them from being applied to the products.
- The products should always be stored and transported in Sanken shipping containers or conductive containers, or be wrapped in aluminum foil.

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In addition, it should be noted that since power devices or IC's including power devices have large self-heating value, the degree of derating of junction temperature affects the reliability significantly.
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